

CERTIFICATE OF COMPLIANCE

RoHS-5 Lead in Solder Exemption

| | |
|-------------------------------|------------------------|
| Power-One Model Series | Description |
| HBC/HBCS | DC/DC Converter |

This document certifies that the power supply model numbers as stated above, manufactured by Power-One, Inc., are in compliance with *Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronics equipment* (RoHS Directives). The stated power supply model numbers are deemed to be compliant in accord with the maximum concentration values issued by the European Union Technical Adaptation Committee (TAC) as shown below:

| Substance | Proposed Maximum Concentration | Actual Concentration |
|---------------------------------------|---------------------------------------|-----------------------------|
| Lead – Pb | 0.1 % | >0.1 % |
| Mercury - Hg | 0.1 % | <0.1 % |
| Cadmium - Cd | 0.01% | <0.01% |
| Hexavalent Chromium Cr (VI) | 0.1 % | <0.1 % |
| Polybrominated biphenyls – PBB | 0.1 % | <0.1 % |
| Polybrominated diphenyl ethers - PBDE | 0.1 % | <0.1 % |

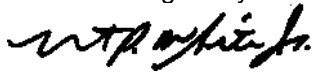
Certain components of the part numbers as stated above are exempted under Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronics equipment (RoHS Directive). The components, including solder, are deemed as exempted in accordance with the following exemptions listed in the Annex of the RoHS Directive:

6. -Lead as an alloying element in steel containing up to 0.35 % lead by weight, aluminum containing up to 0.4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
7. -Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85 % lead).
 -Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
 -Lead in electronic ceramic parts (e.g. piezoelectronic devices).

Effective manufacturing dates: All

This document also certifies that the materials declaration as provided by Power-One, Inc. is accurate.

Authorized signatory for Power-One, Inc. :



Mr. Robert P. White Jr. – Director of Safety and Environmental Compliance

Date: February 2, 2006